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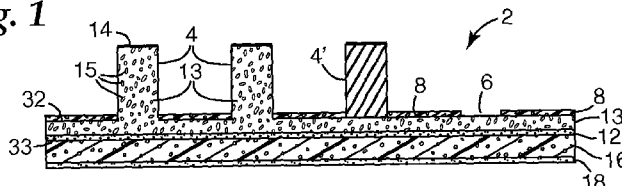
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(54) **Title:** POLISHING PADS INCLUDING PHASE-SEPARATED POLYMER BLEND AND METHOD OF MAKING AND USING THE SAME

Fig. 1

(57) **Abstract:** Polishing pads containing a phase-separated polymer blend, and methods of making and using such pads in a polishing process. In one exemplary embodiment, the polishing pads include a multiplicity of polishing elements integrally formed in a sheet. In another exemplary embodiment, the polishing elements are bonded to a support layer, for example by thermal bonding. In certain embodiments, the polishing pad may additionally include a compliant layer affixed to the support layer, and optionally, a polishing composition distribution layer.